

Title (en)

CONDUCTIVE PROPYLENE RESIN COMPOSITION AND PARTS CONTAINER

Title (de)

LEITFÄHIGE PROPYLENHARZZUSAMMENSETZUNG UND BEHÄLTER FÜR TEILE

Title (fr)

COMPOSITION DE RESINE DE PROPYLENE CONDUCTRICE ET CONTENEUR A PIECES

Publication

EP 0899298 B1 20020213 (EN)

Application

EP 97920947 A 19970512

Priority

- JP 9701580 W 19970512
- JP 11787696 A 19960513

Abstract (en)

[origin: EP0899298A1] A conductive propylene resin composition, which is used for packaging and automatic feeding of parts which is unlikely be electrically charged, which is resistive to a baking treatment and which does not produce wastes and can reduce a material cost and a processing cost, is provided. The composition contains of (1) a % by weight of a propylene polymer with a portion having not less than 95 % by weight of crystallinity that occupies not less than 60 % by weight of the propylene polymer, and contains not more than 20 % by weight of ethylene; (2) b % by weight of a propylene random copolymer which has a tensile elongation of not less than 100 % and contains 1 to 7 % by weight of ethylene; and (3) c % by weight of an electrically conductive filler, wherein the following relationships are satisfied: $a + b + c = 100$, $0.5 \leq a / b \leq 2.0$ and $10 \leq c \leq 30$.

IPC 1-7

C08L 23/00; **C08K 3/00**

IPC 8 full level

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Citation (examination)

US 4522994 A 19850611 - CHIBA HIROMASA [JP], et al

Cited by

US7390563B2; WO0236667A1

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